

REMARKS

Claims 2-16 are pending in this application, of which claims 2-7 have been amended.

Claims 11-16 are newly-added. No new claims have been added.

Claims 1-10 stand rejected under 35 USC §103(a) as unpatentable over U.S. Patent 5,677,570 to Kondoh et al. (hereinafter "**Kondoh et al.**") in view of U.S. Patent 6,328,176 to Zivic (hereinafter "**Zivic**").

Applicant respectfully traverses this rejection.

Kondoh et al. discloses a semiconductor integrated circuit device for high-frequency or high-speed circuitry having stabilized characteristics and reduced influence on surrounding devices. Ground leads extending from a metal substrate or metal layer for mounting ICs for high-frequency or high-speed circuitry are disposed adjacent to at least one side of signal leads 1a, 1b and a width W or a space S of at least a part of the leads are set to inherent values for reducing the inductance of ground leads 2a. Further, passive condenser chips 7a, 7b for short-circuiting or blocking a high frequency signal are mounted on the metal substrate to suppress high-frequency component signals flowing through power supply leads 3a, 3b and ground leads 2a.

The Examiner has admitted that **Kondoh et al.** fails to show the condenser chips 7a, 7b stacked on the semiconductor chip 5, but has cited **Zivic** for teaching this feature.

Zivic discloses a multilayer ceramic condenser chip mounted on a second chip "comprising one of a self-limiting condenser and a Varicon diode" for the purpose of providing a

parallel connection of two discrete components for protection against voltage spikes and both low and high frequency disturbances.

Fig. 3 of Kondoh et al. shows separate condenser chips 7a, 7b for each condenser and only a single circuit block on the semiconductor chip 5, in contrast to the present invention as recited in claim 2, which recites a plurality of circuit blocks found in the semiconductor chip and a plurality of condensers in the condenser chip corresponding to the circuit blocks.

Kondoh et al. fails to disclose a plurality of circuit blocks formed in the semiconductor chip, as recited in claim 3 of the instant application.

Fig. 3 of Kondoh et al. fails to show a “first power supply pad provided on a connecting line extending from one of said power supply line and said ground line to said circuit block”, as recited in claim 4 of the instant application. In Kondoh et al., the circuit block is connected to the power supply only through the condenser chips.

Kondoh et al. fails to disclose that the condenser chip 7a, 7b are connected to an electrode pad of the semiconductor chip 5 by flip chip bonding, as recited in claim 5 of the instant application.

Regarding claim 7, the Examiner has erroneously referred to pad 6d shown in Fig. 3 of Kondoh et al. as the “fourth electrode pad of said condenser chip” recited therein. Pad 6d is shown in Kondoh et al. as appearing on the semiconductor chip 5.

Accordingly, claims 2-5 and 7 have been amended to be in independent form, while claim 1 has been canceled. Claim 6 has been amended to depend from claim 2 and claim 7 has been

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amended to depend from claim 4.

Regarding claim 9, Kondoh et al. fails to disclose an inductor connected to at least one of a power line and a ground line “formed by connecting said first electrode pad of said first semiconductor chip and said second electrode pad of said semiconductor chip by a bonding wire”, as recited therein.

Thus, the 35 USC §103(a) rejection should be withdrawn.

New claims 11-12, depending from claims 2-3, respectively, have been added. New claims 13-15, depending from claims 3-5, respectively, have been added. New claims 16 and 17, depending from claims 5 and 16, respectively, have been added.

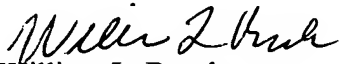
In view of the aforementioned amendments and accompanying remarks, claims 2-16, as amended, are in condition for allowance, which action, at an early date, is requested.

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosures: Amendment Transmittal